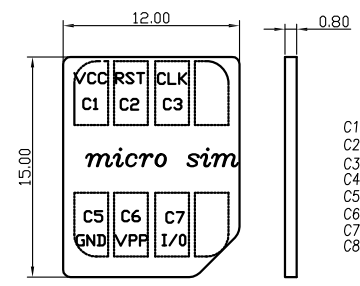
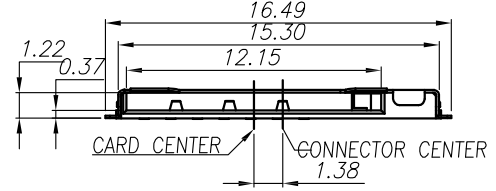
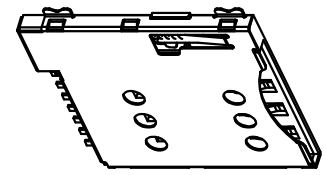
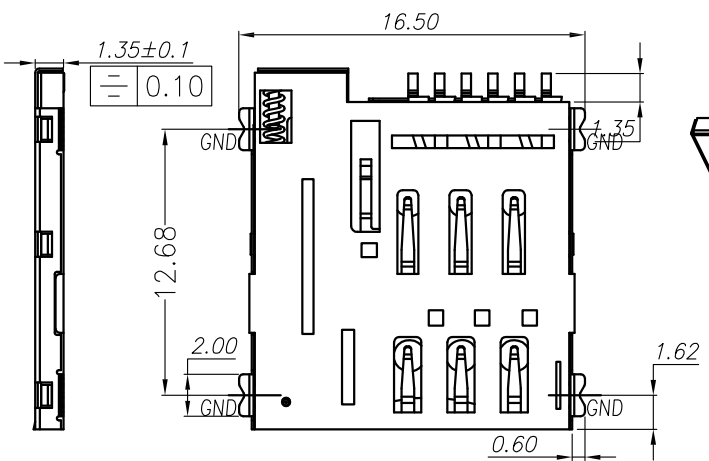
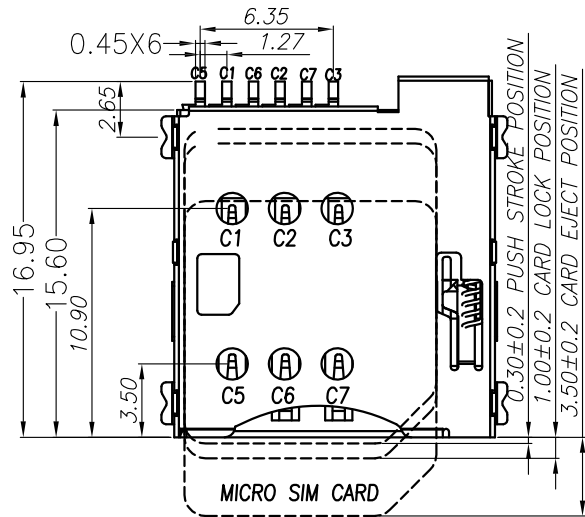
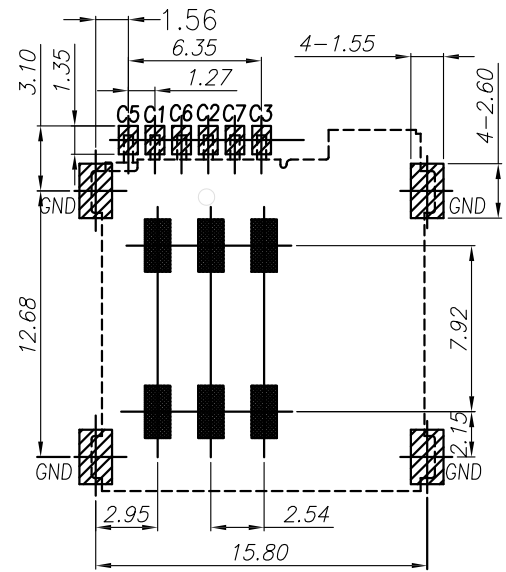


REV.	ECN.NO.	APPD.
A	/	/

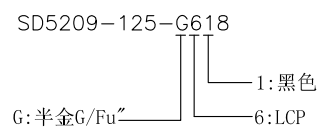


- C1:VCC
- C2:RST
- C3:CLK
- C4:RESERVED
- C5:GND
- C6:VPP
- C7:I/O
- C8:RESERVED

MICRO SIM CARD



- \*Electrical Characteristics:  
Contact Current Rating:0.5 Amperes.  
Dielectric Withstanding Voltage:AC500V r.m.s.  
Insulation Resistance:1000 MΩ Minimum.  
Contact Resistance:100 mΩ Maximum.
- \*Environmental:  
Operating Temperature:-25°C~+90°C.
- \*Environmental:  
Mating Cycles:5000~10,000 Insertions.
- \*Mechanical Characteristics:  
Card Push Insertion/Out Force:1.4kgf. MAX  
Contact Separation Force:0.20kgf Minimum.
- \*Material:  
Insulator:HI-Temp Plastic UL 94V-0 Rated.  
Contact:Copper Alloy(t=0.15mm).  
Shell:Stainless Steel(t=0.20mm).  
Spring:SWP.



TOLERANCE UNLESS OTHERWISE SPECIFIED	
.XXX ±0.10	.X ±3'
.XX ±0.20	.XX' ±2'
.X ±0.30	

**FLW** 深圳市华联威电子科技有限公司  
HUA LIAN WEI TECHNOLOGY ELECTRONICS CO.;LTD.

APPROVED		PART NAME:	MICRO SIM卡 卡座 6PIN 自弹式卡槽 手机SIM卡座 PUSH SIM小卡 6P			
CHECKED		PART No:	SD5209-125-G618		C	
DRAWN	chenyiting	PROJECTION:	UNIT:	SCALE	SHEET	REV.
DATE	2023. 04. 18		mm	1:1	10F1	A